

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L26	74	((copper OR Cu) WITH (Nickel OR Ni) WITH plating WITH metallization) AND ("257" OR "438").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 10:23
S94	74	((copper OR Cu) WITH (Nickel OR Ni) WITH plating WITH metallization) AND ("257" OR "438").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/27 16:59
S93	2	("4763829").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/27 13:14
S92	4	((("6458622") or ("6545355"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/27 13:11
S91	88	(pad WITH gold WITH "1" WITH "mu.m") AND ("257" OR "438").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/27 12:29

S80	30	S89 AND ground	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/26 20:31
S89	82	S88 AND power	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/26 20:30
S88	189	S87 AND (copper OR Cu) AND (gold OR Au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/26 20:30
S87	235	(pad WITH solder WITH barrier WITH layer WITH metal) AND ("257" OR "438").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/26 20:29
S86	30	"pad comprises solder"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/05 15:18
S85	41	S84 AND wire\$1bond	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/05 13:13

S84	763	contact WITH pad WITH compris\$3 WITH solder AND ("257" OR "438").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/05 13:08
S82	2	("6921980").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/05 13:07
S81	2	("6267290").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/04/05 13:05
S80	1394	((post ADJ\$1 passivation) OR post-passivation) WITH (metal OR metallization)) AND nitride AND pad AND polyimide AND ("257" OR "438").clas.	US-PGPUB; USPAT	OR	ON	2007/03/31 13:17
S78	218	S77 AND ("257" OR "438").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 12:25
S77	254	(wire\$1bond\$3 WITH (Au OR gold)) AND (pad WITH (copper OR Cu)) AND (pad WITH (gold OR Au))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 12:25

S76	2	(wire\$1bond\$3 WITH (Au OR gold)) AND (438/238,381,382).ccls.	US-PGPUB; USPAT; USOCR, EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 12:22
S75	39	(wire\$1bond\$3 WITH (Au OR gold)) AND (438/601,612).ccls.	US-PGPUB; USPAT; USOCR, EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 12:18
S74	25	("5134460" "5731624" "5795819" "5864946" "6133136" "6187680").PN. OR ("6451681").UPPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/28 11:38
S73	2	("6451681").PN.	US-PGPUB; USPAT; USOCR, EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/27 16:58
S72	30	("4113550" "4152195" "4378383" "4411735" "4560436").PN. OR ("4827326").UPPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/27 16:57
S70	10	("4827326" "5552343" "5731243" "6261704" "6287950" "6303459" "6361704").PN. OR ("6709965").UPPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/27 15:37
S69	2	("6187680" "6709965").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/27 15:32
S68	949	((pad ADJ\$2 (above) ADJ\$2 passivation) SAME (wire OR wire-bond\$3)) AND (438/601,132,612,654).ccls.	US-PGPUB; USPAT	OR	ON	2007/03/27 15:25
S67	988	((pad ADJ\$2 (over OR above) ADJ\$2 passivation) SAME (wire OR wire-bond\$3)) AND (438/601,132,612,654).ccls.	US-PGPUB; USPAT	OR	ON	2007/03/27 15:25
S66	929	((pad ADJ\$2 "over" ADJ\$2 passivation) SAME (wire OR wire-bond\$3)) AND (438/601,132,612,654).ccls.	US-PGPUB; USPAT	OR	ON	2007/03/27 15:25

S65	929	((pad AD.\$2 over AD.\$2 passivation) SAME (wire OR wire-bond\$3)) AND (438/601,132,612,654).ccls.	US-PGPUB; USPAT	OR	ON	2007/03/27 15:22
S60	0	"pad over said passivation" AND wire\$1bond\$3	US-PGPUB; USPAT	OR	ON	2007/03/27 15:14
S57	8	power WITH bus WITH (Au OR gold) WITH compris\$3	US-PGPUB; USPAT	OR	ON	2007/03/27 14:49
S1	137	((MOU-SHIUNG) near2 (LIN)).INV.	US-PGPUB; USPAT	OR	ON	2007/03/27 14:49
S56	14	S55 AND wire\$1bond\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/26 12:56
S55	38	S54 AND solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/26 12:56
S54	123	(power WITH ground WITH bus WITH capacitor) AND (capacitor WITH (chip OR die OR semiconductor))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/26 12:56
S51	518	(power WITH ground WITH bus) AND (capacitor WITH (chip OR die OR semiconductor))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/26 12:55

S53	72	S52 AND ((wire WITH bond\$3) OR wire-bond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/26 12:53
S52	109	S51 AND solder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/26 12:53
S49	2	("6921980").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/26 12:50
S48	11	("20020176989" "5079069" "5261153" "5282312" "5583321" "5590460" "5800575" "6274224" "6349456" "6699748" "6724638").PN. OR ("7092237"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/25 12:10
S47	4425	(257/686,685,723).COLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/28 18:00
S46	2	("6495442").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/28 18:00

S45	72	(second OR plurality OR multiple) WITH (wiring OR interconnection OR metallization) WITH (post OR above) WITH passivation AND (die OR chip) AND "257".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 16:12
S44	5	(second OR plurality OR multiple) WITH thick WITH (wiring OR interconnection OR metallization) WITH (post OR above) WITH passivation AND (die OR chip) AND "257".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 16:05
S43	1	"second thick metal lines" AND "first thick metal lines" AND interconnection AND "257".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 16:00
S42	27	"gold pad" WITH ("wire bond" OR "wire bonding" OR "wire bonded" OR wirebond\$3 OR wire-bond\$3) AND "257".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 15:58
S41	6	(aluminum WITH pad WITH "metal cap") AND "257".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 15:24
S40	93	(aluminum WITH pad WITH cap) AND "257".clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 12:49

S39	1	("6303423").PN.	USPAT	OR	OFF	2006/09/28 12:48
S38	93	(discrete WITH capacitor WITH (mount\$3 OR attach\$3 OR build\$3) WITH (die OR chip OR substrate)) AND capacitor AND ((power AND ground) OR power/ground) AND decoupl\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 12:13
S37	888	(capacitor WITH (mount\$3 OR attach\$3 OR build\$3) WITH (die OR chip OR substrate)) AND capacitor AND ((power AND ground) OR power/ground) AND decoupl\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 12:00
S36	930	((passive OR capacitor) WITH (mount\$3 OR attach\$3 OR build\$3) WITH (die OR chip OR substrate)) AND capacitor AND ((power AND ground) OR power/ground) AND decoupl\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 12:00
S35	1	((passive OR capacitor) WITH (mount\$3 OR attach\$3 OR build\$3) WITH (die OR chip OR substrate)) AND capacitor AND ((power AND ground) OR power/ground) AND decoupl\$3 AND ((wirebond\$3 OR wire-bond\$3 OR "wire bond" OR "wire bonding" OR "wire bonded") WITH (Au OR gold)) AND ((pad OR electrode) WITH (Al OR aluminum)) AND ((plurality OR multiple) WITH (interconnection OR wiring OR lines) WITH level WITH dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 11:59

S34	1	(discrete WITH (passive OR capacitor) WITH (mount\$3 OR attach\$3 OR build\$3) WITH (die OR chip OR substrate)) AND capacitor AND ((power AND ground) OR power/ground) AND decoupl\$3 AND ((wirebond\$3 OR wire-bond\$3 OR "wire bond" OR "wire bonding" OR "wire bonded") WITH (Au OR gold)) AND ((pad OR electrode) WITH (Al OR aluminum)) AND ((plurality OR multiple) WITH (interconnection OR wiring OR lines) WITH level WITH dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 11:57
S33	611	(discrete WITH (passive OR capacitor) WITH (mount\$3 OR attach\$3 OR build\$3) WITH (die OR chip OR substrate)) AND capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/28 11:53
S32	2	("20040183209").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/28 11:49
S31	27	("20010023993" "20010031548" "20020011656" "20020063340" "20020185721" "20020227753" "20030062629" "20030085466" "20030209806" "5209817" "5407864" "5817541" "5834844" "6002178" "6181569" "6187680" "6200888" "6287893" "6316830" "6350632" "6350633" "6362087" "6365501" "6479900" "6539624" "6590291" "6627824" "6653217").PN. OR ("6921980"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/27 10:36
S30	1	("6921980").PN.	USPAT	OR	OFF	2006/09/27 09:36

S29	6	("20020113323" "6624501" "6873038").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/27 09:36
S28	4	2002-299496 OR 2002-299496	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/27 09:20
S27	6	(("6303423") or ("6515369") or ("6495442") or ("6383916") or ("6184574") or ("6504236")).PN.	USPAT	OR	OFF	2006/09/27 09:13
S26	265	("257" OR "438").clas. AND (discrete WITH capacitor WITH (mount\$3 OR attach\$3 OR connect\$3) WITH (chip OR die OR substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/27 09:11
S24	33	(257/724,728,516,528,532,535,207,203).ccis. AND (discrete WITH capacitor WITH (mount\$3 OR attach\$3 OR connect\$3) WITH (chip OR die OR substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/27 08:54
S25	46	("3566203" "4744008" "4945399" "4949163" "4984065" "4994895" "5049979" "5055966" "5119172" "5148265" "5148266" "5281846" "5311057").PN. OR ("5633785").UPFN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/27 08:38
S23	41	(chip OR die OR IC OR "integrated circuit") SAME (interconnect\$4 OR wire OR wiring OR metallization) AND passivation AND (discrete WITH capacitor WITH (mount\$3 OR attach\$3 OR solder\$3)) AND (wire-bond\$3 OR "wire bond" OR "wire bonding" "wire bonded" OR wirebond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/27 08:23

S22	281	(chip OR die OR IC OR "integrated circuit") SAME (interconnect\$4 OR wire OR wiring OR metallization) AND passivation AND (discrete WITH (mount\$3 OR attach\$3 OR solder\$3)) AND (wire-bond\$3 OR "wire bond" OR "wire bonding" "wire bonded" OR wirebond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:56
S12	18	(chip OR die OR IC OR "integrated circuit") SAME substrate SAME (interconnect\$4 OR wire OR wiring OR metallization) AND passivation AND ("discrete capacitor" WITH (mount\$3 OR attach\$3 OR solder\$3)) AND (wire-bond\$3 OR "wire bond" OR "wire bonding" "wire bonded" OR wirebond\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:55
S21	44	("4811082" "5239198" "5528209" "5600257" "5608261" "5629383" "5702984" "5764070" "5772451" "5811868" "5870289" "5903050" "5926359" "5974662" "5977640" "6027980" "6075712").PN. OR ("6222246").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 16:25
S20	33	("4734818" "4744088" "4754366" "4882656" "5034850" "5049979" "5095402" "5272590" "5304506" "5366931" "5498906" "5583739" "5587333" "5606197" "5656834" "5668399" "5701032" "5814892" "5903050").PN. OR ("6222260").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 16:08
S19	47	("5734198" "6054754").PN. OR ("6373127").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 16:06
S18	68	("4945399" "4989117" "4994936" "5049979" "5103283" "5134539" "5274270" "5311057").PN. OR ("5528083").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 16:01
S17	22	("4598307" "5010445" "5049979" "5115298" "5258329" "5306952" "5457062").PN. OR ("5629240").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 15:59

S16	15	("20020135049" "20040183209" "5313693" "5528083" "5633785" "6005778" "6222246" "6222260" "6303423" "6335566" "6373127" "6563192" "6611434" "6670692" "6853087").PN. OR ("7091607").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 15:54
S15	31	("5055907" "5106461" "5212403" "5372967" "5501006" "5576680" "5635767" "5686764" "5884990" "6008102" "6040226").PN. OR ("6303423").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 15:52
S14	47	("0375154" "4249196" "4288841" "4451845" "4453176" "4453199" "4454529" "4527185" "4567643" "4598307" "4617586" "4636918" "4639826" "4654694" "4680613" "4714952" "4744008" "4749120" "4819056" "4820013" "4851862").PN. OR ("5049979").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 15:45
S13	46	("3566203" "4744008" "4945399" "4949163" "4984065" "4994895" "5049979" "5055966" "5119172" "5148265" "5148266" "5281846" "5311057").PN. OR ("5633785").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/26 14:18
S11	2186	(257/532,535).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/26 13:52
S10	28	((chip OR die) AND (discrete NEAR\$2 capacitor) AND passivation AND (wirebond\$3 OR wire-bond\$3 OR wire)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 19:54

S8	1868	((chip OR die) AND (discrete NEAR\$2 capacitor) AND (wirebond\$3 OR wire-bond\$3 OR wire)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 19:54
S9	28	((chip OR die) AND (discrete NEAR\$2 capacitor) AND passivation AND (wirebond\$3 OR wire-bond\$3 OR wire)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 19:53
S7	1037	S5 AND capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 19:50
S5	3863	(257/723,724).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/22 19:38
S4	6	((("5789303") or ("6051489") or ("5789303") or ("6146958"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/22 19:33
S3	12	("6184574" "6303423" "6383916" "6495442" "6504236" "6515369").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 19:30

S2	33	S1 AND discrete AND capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/22 19:28
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